

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Device	Value	Units
TOTAL DEVICE				
T_{STG}	Storage Temperature	All	-40 to +100	$^\circ\text{C}$
T_{OPR}	Operating Temperature	All	-40 to +85	$^\circ\text{C}$
T_{SOL}	Lead Solder Temperature	All	260 for 10 sec	$^\circ\text{C}$
V_{ISO}	Isolation Surge Voltage	All	4000	Vac(RMS)
C_{IO}	Maximum Input/Output Capacitance	All	1.0	pF
R_{IO}	Maximum Input/Output Resistance	All	10^{12}	Ω

Electrical Characteristics ($T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ unless otherwise specified)**Input Characteristics**

Symbol	Parameters/ Test Conditions	Connection	Limit	HSR312	HSR312L	HSR412	HSR412L	Units
$I_{F(ON)}$	Control Current	Series or Parallel	Max.	2.0	2.0	3.0	3.0	mA
$I_{F(OFF)}$	Control Current for Off-State Resistance ($T_A = 25^{\circ}\text{C}$)	Series or Parallel	Min.	0.4	0.4	0.4	0.4	mA
I_F	Control Current Range	Series or Parallel	Min.	2.0	2.0	3.0	3.0	mA
			Max.	25	25	25	25	
V_R	Reverse Voltage	Series or Parallel	Min.	7	7	7	7	V
V_F	Forward Voltage ($I_F = 10\text{mA}$)	Series or Parallel	Max.	1.6	1.6	1.6	1.6	V

Output Characteristics

Symbol	Parameters/ Test Conditions	Connection	Limit	HSR312	HSR312L	HSR412	HSR412L	Units
V_{OPR}	Operating Voltage Range	Series or Parallel	Max.	250	250	400	400	V_{DC} or $V_{AC(PEAK)}$
I_L	Load Current $T_A = +40^{\circ}\text{C}$, 5mA control (see Fig. 1 & 2)	Series	Max.	190	170	140	120	mA
		Parallel	Max.	320	300	210	200	
R_{ON}	On-State Resistance $T_A = 25^{\circ}\text{C}$, 50mA pulsed load, 5mA control	Series	Max.	10	15	27	35	Ω
		Parallel	Max.	3	4.25	7	9	
	Off-State Leakage Current $T_A = 25^{\circ}\text{C}$, $\pm 250\text{V}$ for HSR312/L, $\pm 400\text{V}$ for HSR412/L	Series or Parallel	Max.	1.0	1.0	1.0	1.0	μA
I_{LMT}	Current Limit $T_A = +25^{\circ}\text{C}$, 5mA control	Series	Min.	N/A	190	N/A	130	mA
			Max.	N/A	300	N/A	220	
		Parallel	Min.	N/A	330	N/A	260	
			Max.	N/A	560	N/A	440	
T_{ON}	Turn-On Time $T_A = +25^{\circ}\text{C}$ for 50mA, 100VDC load, 5mA control	Series or Parallel	Max.	3.0	3.0	2.0	2.0	mS
T_{OFF}	Turn-Off Time $T_A = +25^{\circ}\text{C}$ for 50mA, 100VDC load, 5mA control	Series or Parallel	Max.	0.5	0.5	0.5	0.5	mS
	Thermal Offset Voltage 5mA control	Series or Parallel	Max.	N/A	N/A	0.5	0.5	mV
C_O	Output Capacitance 50V _{DC}	Series	Max.	50	50	12	12	pF

Isolation Characteristics

Symbol	Characteristics	Test Conditions	Limit	HSR312	HSR312L	HSR412	HSR412L	Units
V_{ISO}	Input-Output Isolation Voltage	$I_{I-O} \leq 2 \mu\text{A}$	Max	4000	4000	4000	4000	V

Typical Performance Curves

Figure 1. Forward Current vs. Forward Voltage

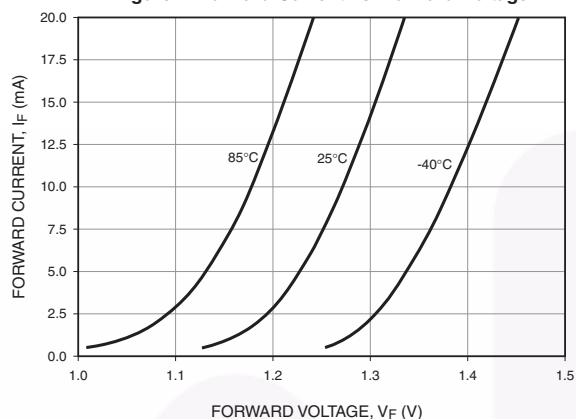


Figure 2. Normalized on Resistance vs. Ambient Temperature

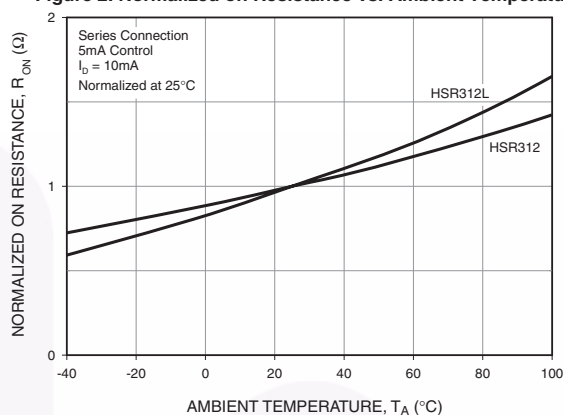


Figure 3. Normalized on Resistance vs. Ambient Temperature

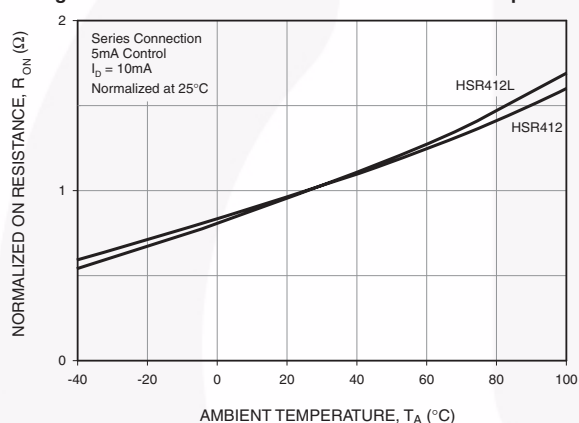


Figure 4. Load Current vs. Voltage Drop

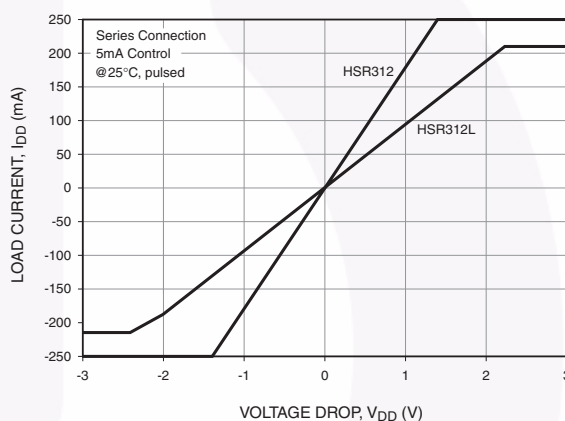


Figure 5. Load Current vs. Voltage Drop

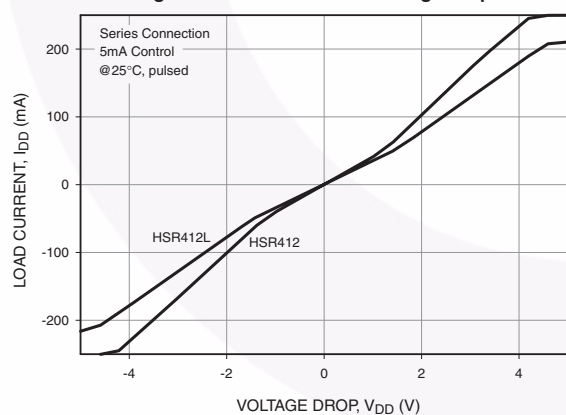
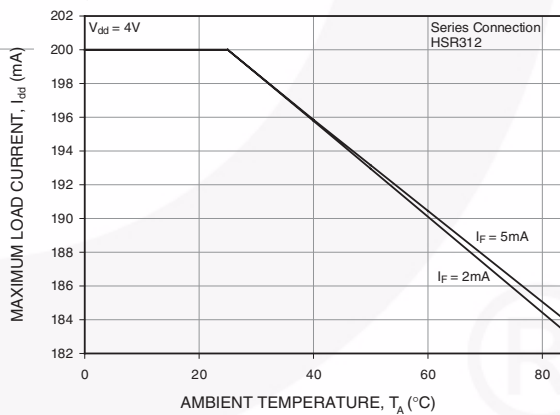


Figure 6. Maximum Load Current Vs Ambient Temperature



Typical Performance Curves (Continued)

Figure 7. Maximum Load Current Vs Ambient Temperature

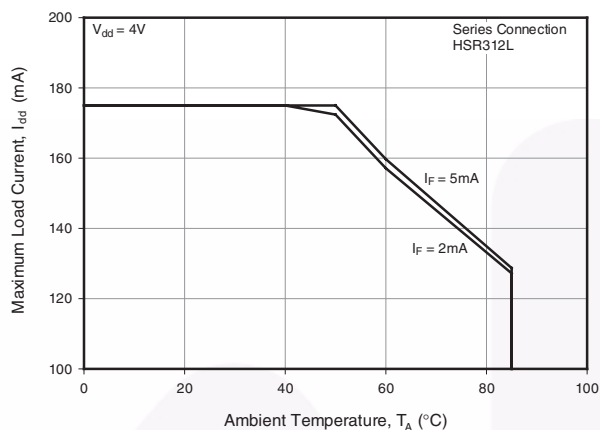


Figure 8. Maximum Load Current Vs Ambient Temperature

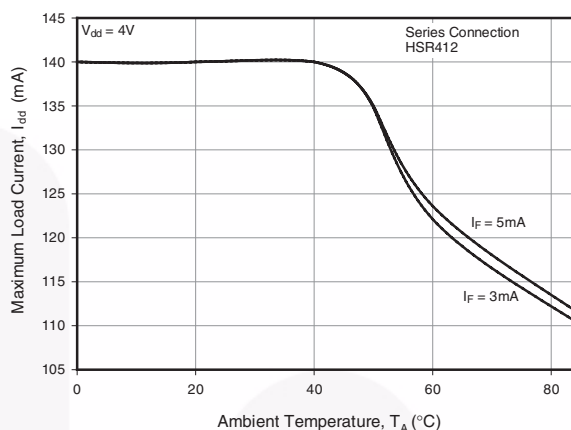


Figure 9. Maximum Load Current Vs Ambient Temperature

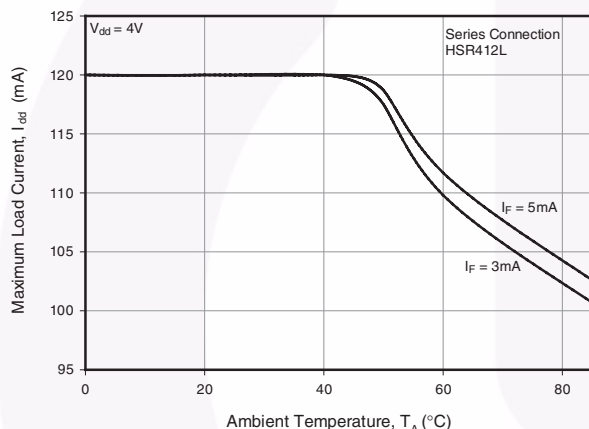


Figure 10. Off State Current vs. Ambient Temperature

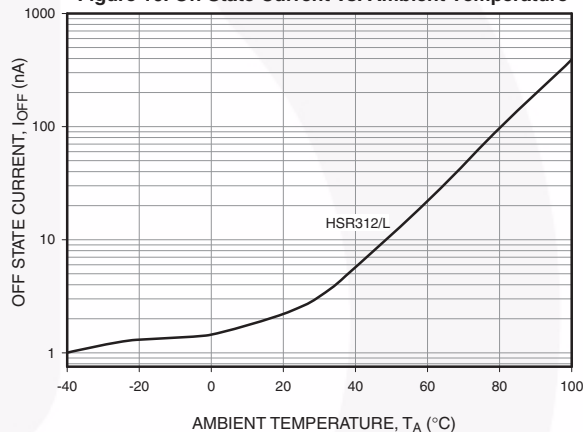


Figure 11. Off State Current vs. Ambient Temperature

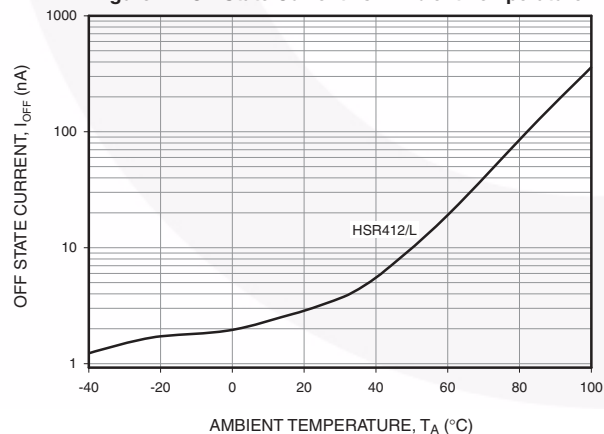
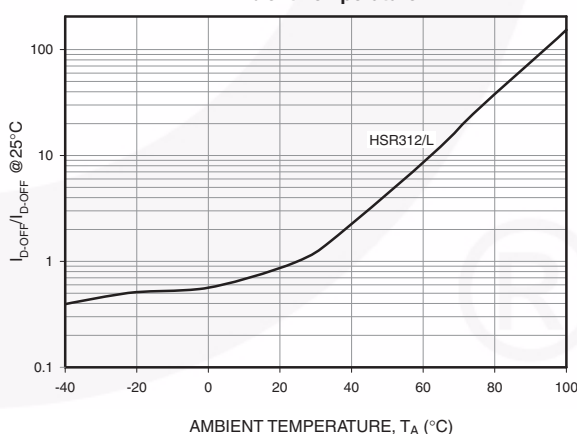
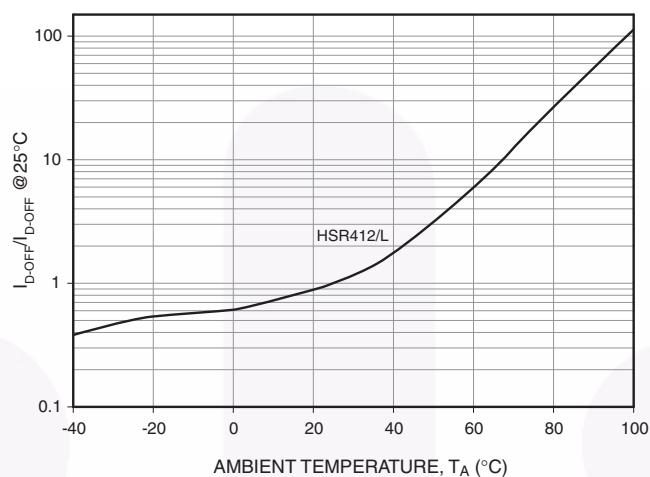


Figure 12. Normalized Off State Leakage vs. Ambient Temperature

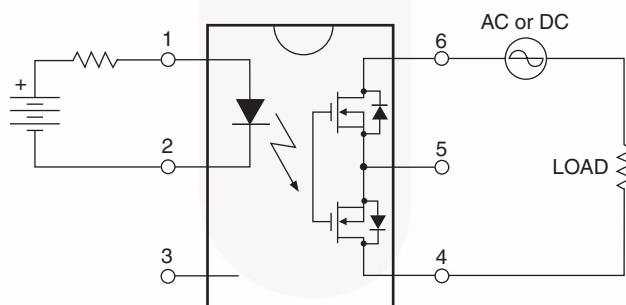


Typical Performance Curves (Continued)

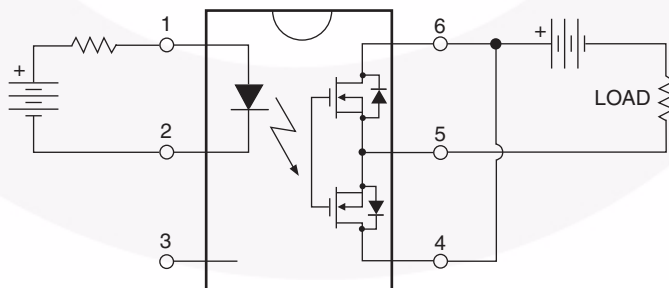
Figure 13. Normalized Off State Leakage vs. Ambient Temperature



Series Connection

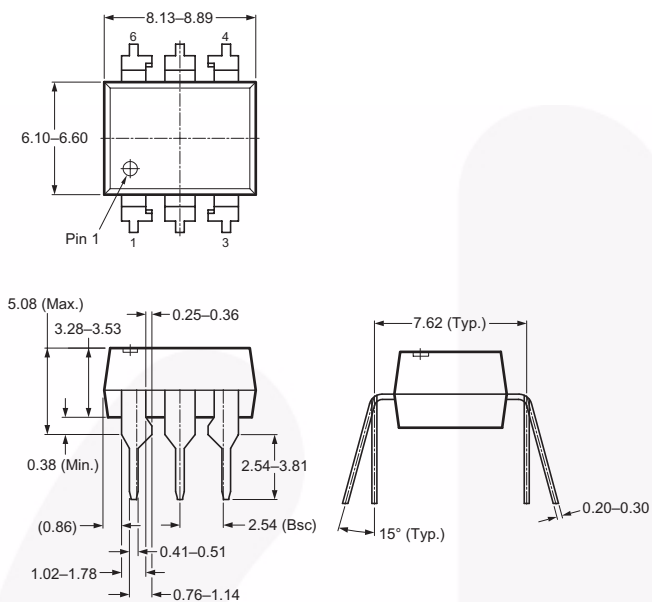


Parallel Connection

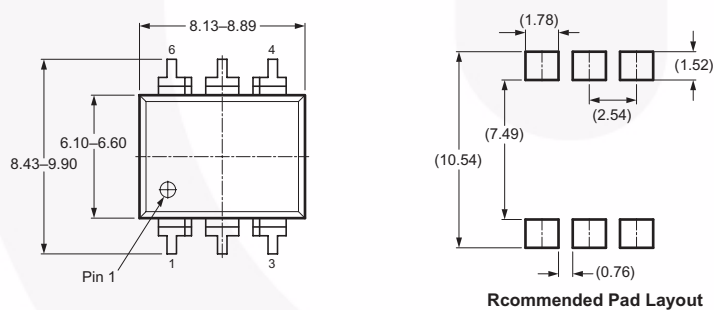


Package Dimensions

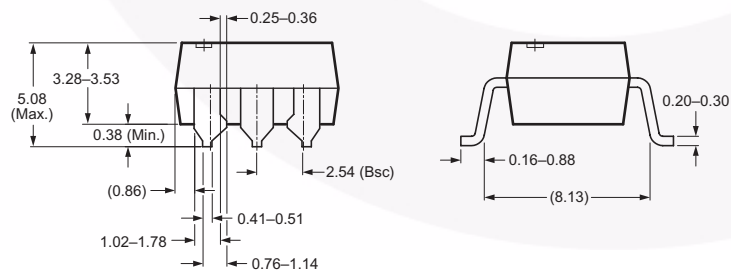
Through Hole



Surface Mount



Recommended Pad Layout

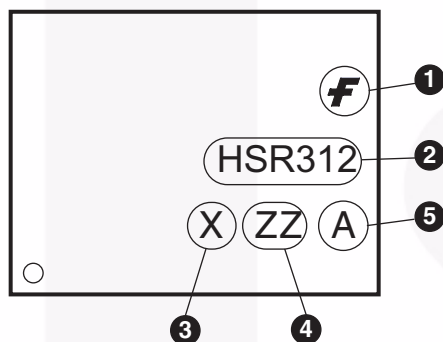


Note:
All dimensions in mm.

Ordering Information

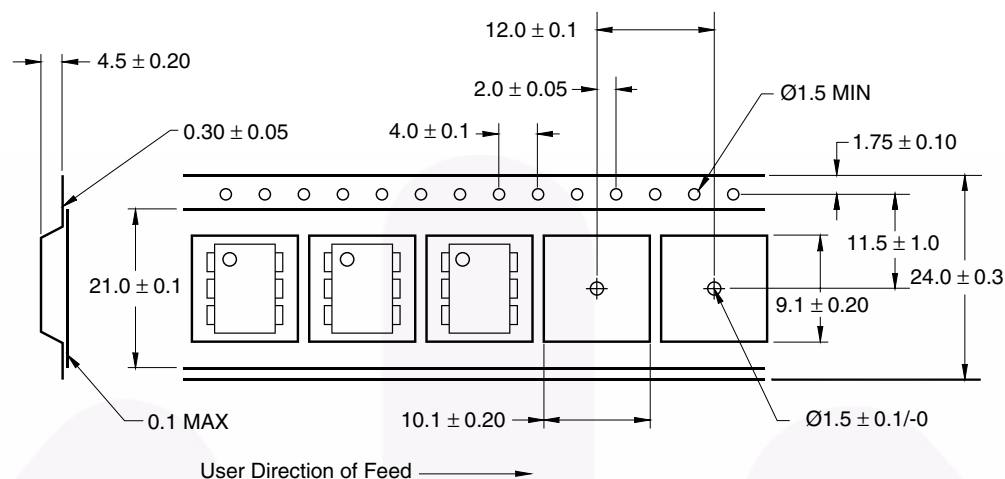
Option	Order Entry Identifier (Example)	Description
No option	HSR312	Standard Through Hole Device
S	HSR312S	Surface Mount Lead Bend
SR2	HSR312SR2	Surface Mount; Tape and Reel

Marking Information

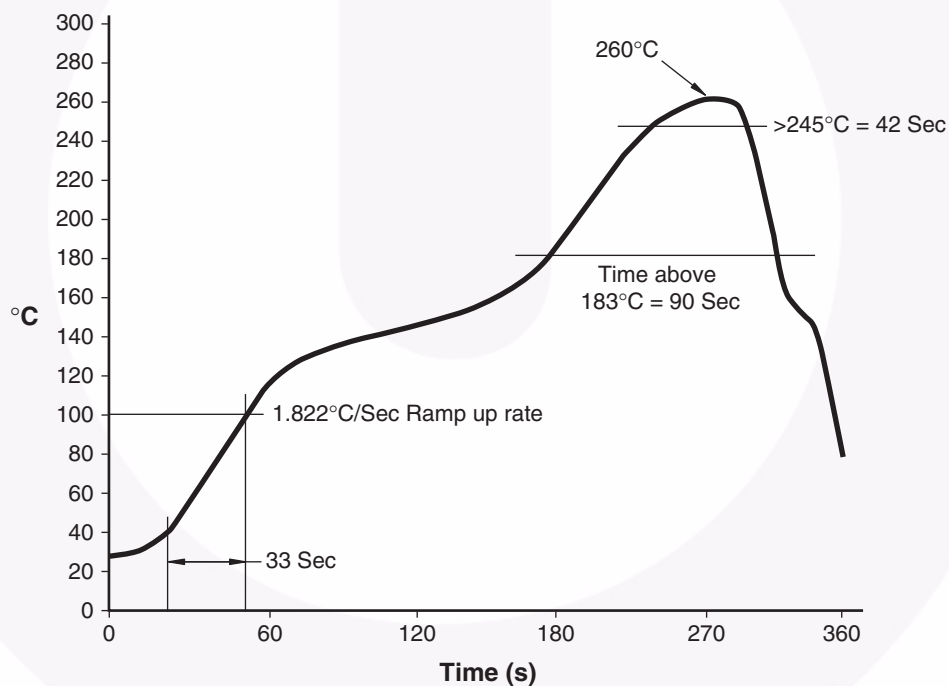


Definitions	
1	Fairchild logo
2	Device number
3	One digit year code, e.g., '3'
4	Two digit work week ranging from '01' to '53'
5	Assembly package code

Carrier Tape Specification



Reflow Profile





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